



FPAM50LH60

PFC SPM[®] 2 Series for 2-Phase Interleaved PFC

Features

- UL Certified No.E209024 (UL1557)
- 600 V - 50 A 2-Phase Interleaved PFC with Integral Gate Driver and Protection
- Very Low Thermal Resistance Using Al₂O₃ DBC Substrate
- Full-Wave Bridge Rectifier and High-Performance Output Diode
- Optimized for 20kHz Switching Frequency
- Built-in NTC Thermistor for Temperature Monitoring
- Isolation Rating: 2500 V_{rms}/min

Applications

- 2-Phase Interleaved PFC Converter

Related Source

- [Will Be Released](#)

General Description

The FPAM50LH60 is a PFC SPM[®] 2 module providing a fully-featured, high-performance Interleaved PFC (Power Factor Correction) input power stage for consumer, medical, and industrial applications. These modules integrate optimized gate drive of the built-in IGBTs to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockout, over-current shutdown, thermal monitoring, and fault reporting. These modules also feature a full-wave rectifier and high-performance output diodes for additional space savings and mounting convenience.

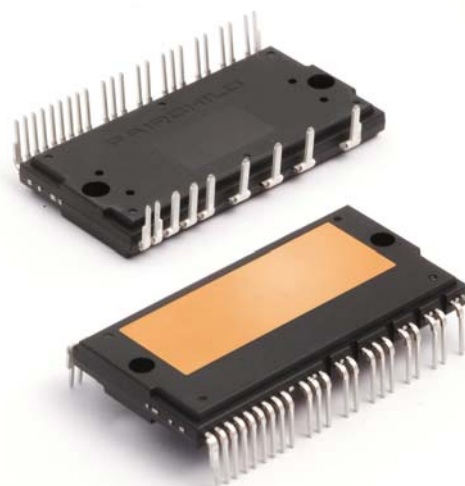


Fig. 1. Package Overview

Package Marking and Ordering Information

| Device | Device Marking | Package | Packing Type | Quantity |
|------------|----------------|-----------|--------------|----------|
| FPAM50LH60 | FPAM50LH60 | S32EA-032 | Rail | 8 |

Integrated Drive, Protection and System Control Functions

- For IGBTs: gate drive circuit, Over-Current Protection (OCP), control supply circuit Under-Voltage Lock-Out (UVLO) Protection
- Fault signal: corresponding to OC and UV fault
- Built-in thermistor: temperature monitoring
- Input interface : active-HIGH interface, works with 3.3 / 5 V logic, Schmitt trigger input

Pin Configuration

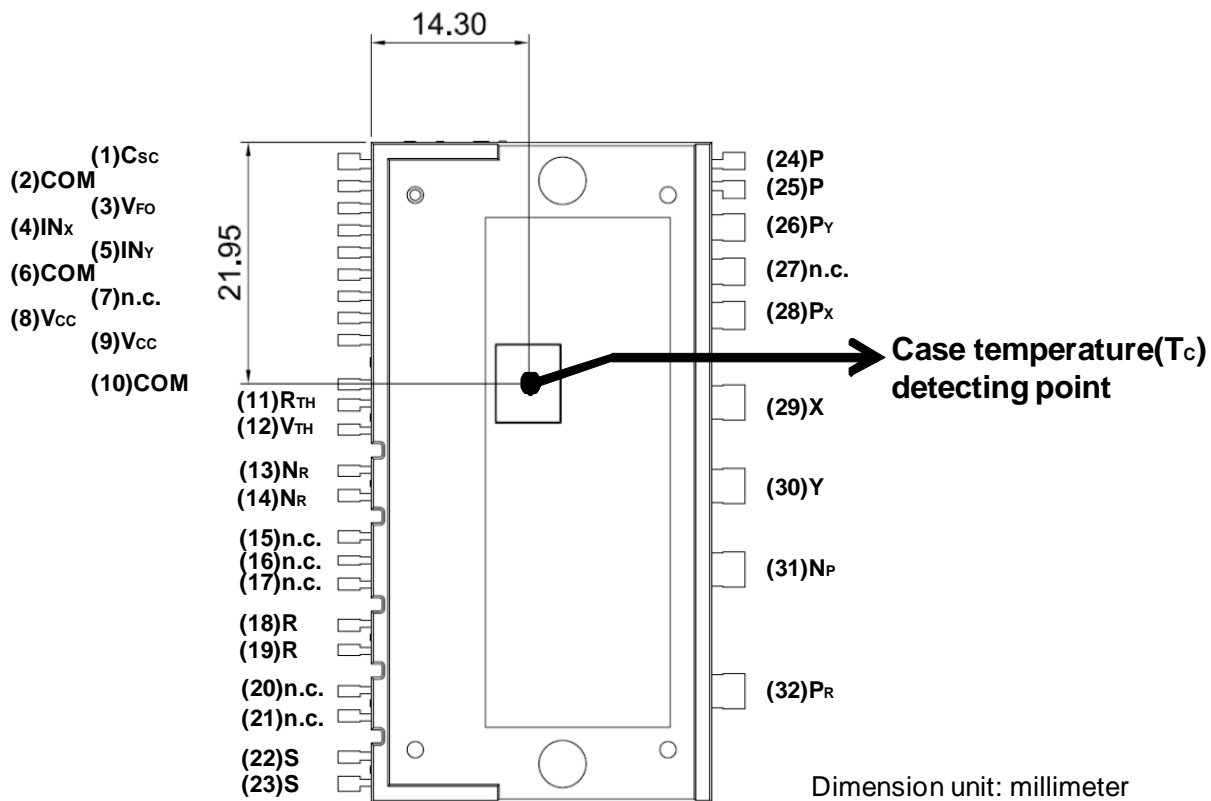


Figure 2. Top View

Pin Descriptions

| Pin Number | Pin Name | Pin Description |
|------------|-----------------|--|
| 1 | C _{SC} | Signal Input for Over-Current Detection |
| 2,6,10 | COM | Common Supply Ground |
| 3 | V _{FO} | Fault Output |
| 4 | IN _X | PWM Input for X IGBT Drive |
| 5 | IN _Y | PWM Input for Y IGBT Drive |
| 7 | N.C | No Connection |
| 8,9 | V _{CC} | Common Supply Voltage of IC for IGBT Drive |
| 11 | R _{TH} | Series Resistor for The Use of Thermistor |
| 12 | V _{TH} | Thermistor Bias Voltage |
| 13,14 | N _R | Negative DC-Link of Rectifier Diode |
| 15,16,17 | N.C | No Connection |
| 18,19 | R | AC Input for R-Phase |
| 20,21 | N.C | No Connection |
| 22,23 | S | AC Input for S-Phase |
| 24,25 | P | Output of Diode |
| 26 | P _Y | Input of Diode |
| 27 | N.C | No Connection |
| 28 | P _X | Input of Diode |
| 29 | X | Output of X Phase IGBT |
| 30 | Y | Output of Y Phase IGBT |
| 31 | N _P | Negative DC-Link of IGBT |
| 32 | P _R | Positive DC-Link of Rectifier Diode |

Internal Equivalent Circuit

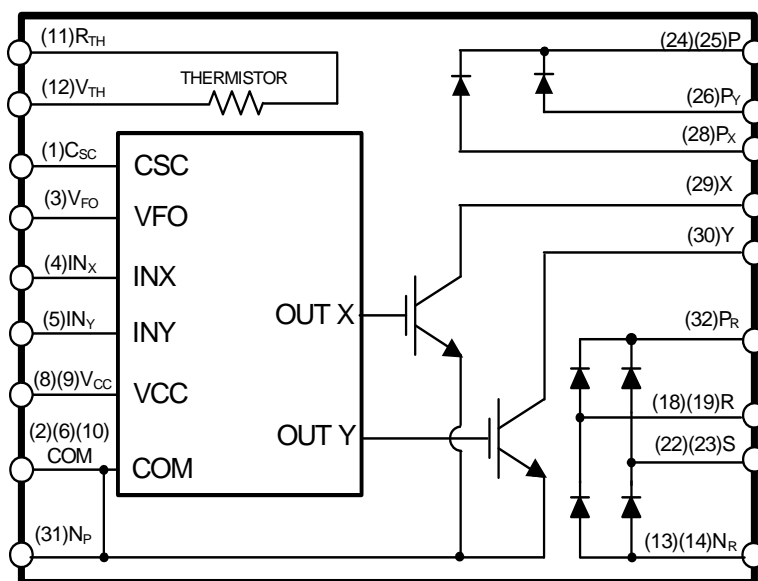


Figure 3. Internal Block Diagram

Absolute Maximum Ratings ($T_J = 25^\circ\text{C}$, unless otherwise specified.)**Converter Part**

| Symbol | Parameter | Conditions | Rating | Unit |
|-----------------|--|--|-----------|------------------|
| V_i | Input Supply Voltage | Applied between R - S | 264 | V_{rms} |
| V_{PN} | Output Voltage | Applied between X - N_P , Y - N_P , P - P_X , P - P_Y | 450 | V |
| $V_{PN(Surge)}$ | Output Supply Voltage (Surge) | Applied between X - N_P , Y - N_P , P - P_X , P - P_Y | 500 | V |
| V_{CES} | Collector-emitter Voltage | Breakdown Voltage between X - N_P , Y - N_P | 600 | V |
| V_{RRM} | Repetitive Peak Reverse Voltage of FRD | Breakdown Voltage between P - P_X , P - P_Y | 600 | V |
| V_{RRMR} | Repetitive Peak Reverse Voltage of Rectifier | Breakdown Voltage between P_R - R, P_R - S, R - N_R , S - N_R | 900 | V |
| $*I_F$ | FRD Forward Current | $T_C = 25^\circ\text{C}$, $T_J < 125^\circ\text{C}$ | 50 | A |
| $*I_{FSM}$ | Peak Surge Current of FRD | Non-Repetitive, 60 Hz Single Half-Sine Wave | 500 | A |
| $*I_{FR}$ | Rectified Forward Current | $T_C = 25^\circ\text{C}$, $T_J < 125^\circ\text{C}$ | 50 | A |
| $*I_{FSMR}$ | Peak Surge Current of Rectifier | Non-Repetitive, 60 Hz Single Half-Sine Wave | 500 | A |
| $\pm *I_C$ | Each IGBT Collector Current | $T_C = 25^\circ\text{C}$, $T_J < 125^\circ\text{C}$ | 50 | A |
| $\pm *I_{CP}$ | Each IGBT Collector Current(Peak) | $T_C = 25^\circ\text{C}$, $T_J < 125^\circ\text{C}$, Under 1 ms Pulse Width | 100 | A |
| $*P_C$ | Collector Dissipation | $T_C = 25^\circ\text{C}$ per IGBT | 135 | W |
| T_J | Operating Junction Temperature | (1st Note 1) | -40 ~ 125 | $^\circ\text{C}$ |

1st Notes:

- The maximum junction temperature rating of the power chips integrated within the PFC SPM® product is 125°C .
- Marking “*” is calculation value or design factor.

Control Part

| Symbol | Parameter | Conditions | Rating | Unit |
|----------|-------------------------------|---------------------------------------|-----------------------|------|
| V_{CC} | Control Supply Voltage | Applied between V_{CC} - COM | 20 | V |
| V_{IN} | Input Signal Voltage | Applied between IN_X , IN_Y - COM | -0.3 ~ $V_{CC} + 0.3$ | V |
| V_{FO} | Fault Output Supply Voltage | Applied between V_{FO} - COM | -0.3 ~ $V_{CC} + 0.3$ | V |
| I_{FO} | Fault Output Current | Sink Current at V_{FO} Pin | 1 | mA |
| V_{SC} | Current Sensing Input Voltage | Applied between C_{SC} - COM | -0.3 ~ $V_{CC} + 0.3$ | V |

Total System

| Symbol | Parameter | Conditions | Rating | Unit |
|-----------|---------------------|---|-----------|------------------|
| T_{STG} | Storage Temperature | | -40 ~ 125 | $^\circ\text{C}$ |
| V_{ISO} | Isolation Voltage | 60 Hz, Sinusoidal, AC 1 Minute, Connect Pins to Heat-Sink Plate | 2500 | V_{rms} |

Thermal Resistance

| Symbol | Parameter | Condition | Min. | Typ. | Max. | Unit |
|----------------|-------------------------------------|--|------|------|------|--------------------|
| $R_{th(j-c)Q}$ | Junction to Case Thermal Resistance | Each IGBT under Operating Condition | - | - | 0.74 | $^\circ\text{C/W}$ |
| $R_{th(j-c)D}$ | | Each Diode under Operating Condition | - | - | 1.13 | $^\circ\text{C/W}$ |
| $R_{th(j-c)R}$ | | Each Rectifier under Operating Condition | - | - | 0.74 | $^\circ\text{C/W}$ |

Electrical Characteristics (T_J = 25°C, unless otherwise specified.)

Converter Part

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------------------|-------------------------------------|--|------|------|------|------|
| V _{CE(SAT)} | IGBT Saturation Voltage | V _{CC} = 15 V, V _{IN} = 5 V, I _C = 50 A | - | 1.7 | 2.2 | V |
| V _{FF} | FRD Forward Voltage | I _F = 50 A | - | 1.9 | 2.4 | V |
| V _{FR} | Rectifier Forward Voltage | I _{FR} = 50 A | - | 1.13 | 1.35 | V |
| I _{RR} | Switching Characteristic | V _{PN} = 400 V, V _{CC} = 15 V, I _C = 25 A, V _{IN} = 0 V ↔ 5 V, Inductive Load (1st Note 3), per IGBT | - | 27 | - | A |
| t _{RR} | | | - | 45 | - | ns |
| t _{ON} | | | - | 772 | - | ns |
| t _{OFF} | | | - | 1117 | - | ns |
| t _{C(ON)} | | | - | 110 | - | ns |
| t _{C(OFF)} | | | - | 125 | - | ns |
| I _{CES} | Collector - Emitter Leakage Current | V _{CES} = 600 V | - | - | 250 | μA |

1st Notes:

3. t_{ON} and t_{OFF} include the propagation delay of the internal drive IC. t_{C(ON)} and t_{C(OFF)} are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

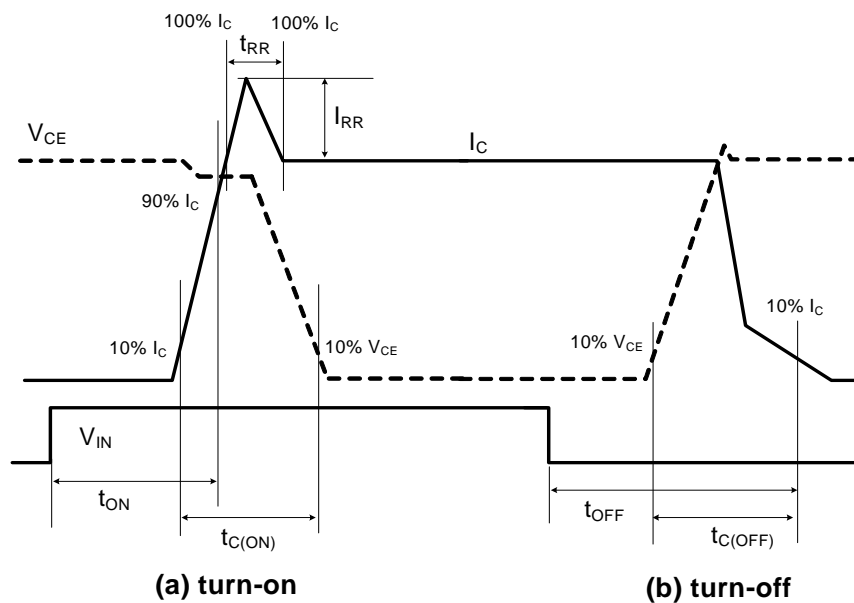


Figure 4. Switching Time Definition

Control Part

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------|---|--|------|------|------|---------------|
| I_{QCC} | Quiescent V_{CC} Supply Current | $V_{CC} = 15\text{ V}$, IN_X , $IN_Y - COM = 0\text{ V}$, Supply current between V_{CC} and COM | - | - | 2.65 | mA |
| I_{PCC} | Operating V_{CC} Supply Current | $V_{CC} = 15\text{ V}$, $f_{PWM} = 20\text{ kHz}$, Duty = 50% Applied to One PWM Signal Input per IGBT Supply Current between V_{CC} and COM | - | - | 7.0 | mA |
| V_{FOH} | Fault Output Voltage | $V_{SC} = 0\text{ V}$, V_{FO} Circuit: 10 k Ω to 5 V Pull-up | 4.5 | - | - | V |
| V_{FOL} | | $V_{SC} = 1\text{ V}$, V_{FO} Circuit: 10 k Ω to 5 V Pull-up | - | - | 0.5 | V |
| $V_{SC(Ref)}$ | Over-Current Protection Trip Level Voltage of CSC Pin | $V_{CC} = 15\text{ V}$ | 0.45 | 0.5 | 0.55 | V |
| UV_{CCD} | Supply Circuit Under-Voltage Protection | Detection Level | 10.5 | - | 13.0 | V |
| UV_{CCR} | | Reset Level | 11.0 | - | 13.5 | V |
| t_{FOD} | Fault-Out Pulse Width | | 30 | - | - | μs |
| $V_{IN(ON)}$ | ON Threshold Voltage | Applied between IN_X , $IN_Y - COM$ | 2.6 | - | - | V |
| $V_{IN(OFF)}$ | OFF Threshold Voltage | Applied between IN_X , $IN_Y - COM$ | - | - | 0.8 | V |
| R_{TH} | Resistance of Thermistor | at $T_{TH} = 25^\circ\text{C}$ (1st Note 4, Figure 5) | - | 47 | - | k Ω |
| | | at $T_{TH} = 100^\circ\text{C}$ (1st Note 4, Figure 5) | - | 2.9 | - | k Ω |

1st Notes:

4. T_{TH} is the temperature of thermistor itself. To know case temperature (T_C), please make the experiment considering your application.

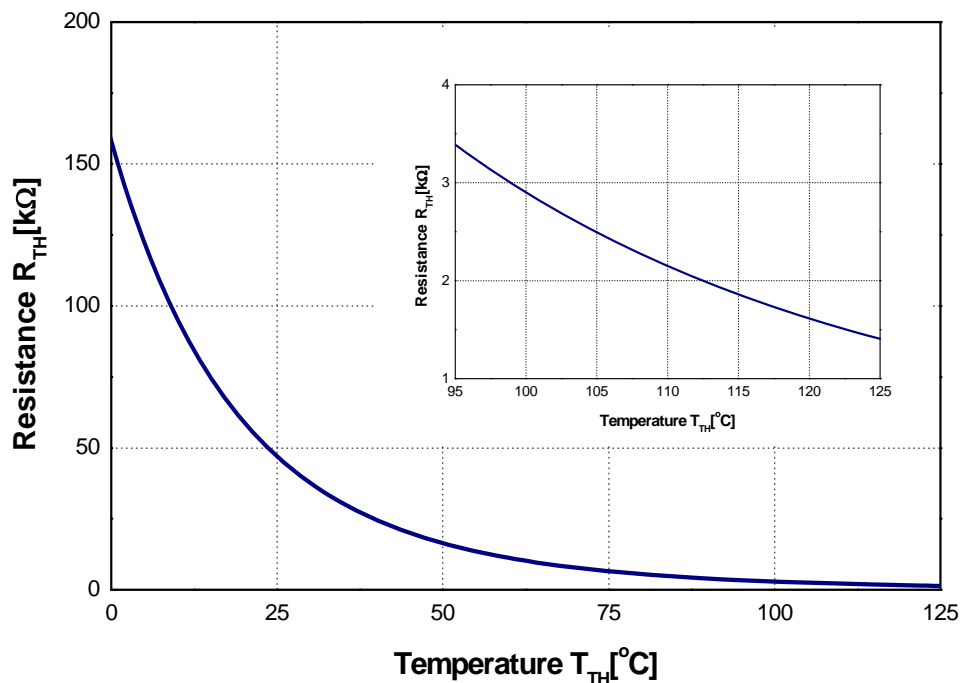
R-T Curve

Figure 5. R-T Curve of The Built-in Thermistor

Recommended Operating Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified.)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--------------|------------------------|---|------|------|------|-----------|
| V_i | Input Supply Voltage | Applied between R - S | 187 | - | 253 | V_{rms} |
| I_i | Input Current | $T_C < 100^\circ\text{C}$, $V_i = 220\text{ V}$, $V_O = 360\text{ V}$, $f_{PWM} = 20\text{ kHz}$ per IGBT | - | - | 21 | A_{rms} |
| V_{PN} | Supply Voltage | Applied between X - N_P , Y - N_P , P - P_X , P - P_Y | - | - | 400 | V |
| V_{CC} | Control Supply Voltage | Applied between V_{CC} - COM | 13.5 | 15.0 | 16.5 | V |
| dV_{CC}/dt | Supply Variation | | -1 | - | 1 | $V/\mu s$ |
| I_{FO} | Fault Output Current | Sink Current at V_{FO} Pin | - | - | 1 | mA |
| f_{PWM} | PWM Input Frequency | $-40^\circ\text{C} < T_J < 125^\circ\text{C}$ per IGBT | - | 20 | - | kHz |

Mechanical Characteristics and Ratings

| Parameter | Conditions | | Min. | Typ. | Max. | Unit |
|-----------------|--------------------|----------------------|------|------|------|---------|
| Mounting Torque | Mounting Screw: M4 | Recommended 0.98 N•m | 0.78 | 0.98 | 1.17 | N•m |
| | | Recommended 10 kg•cm | 8 | 10 | 12 | kg•cm |
| Device Flatness | See Figure 6 | | 0 | - | +150 | μm |
| Weight | | | - | 32 | - | g |

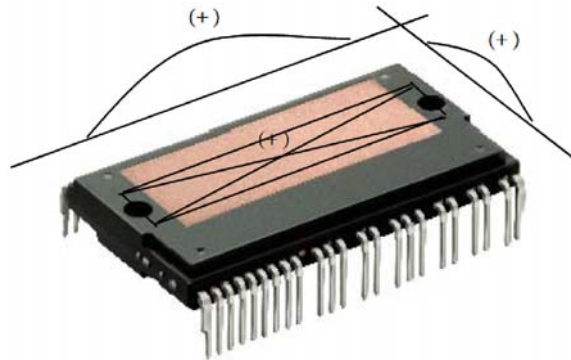
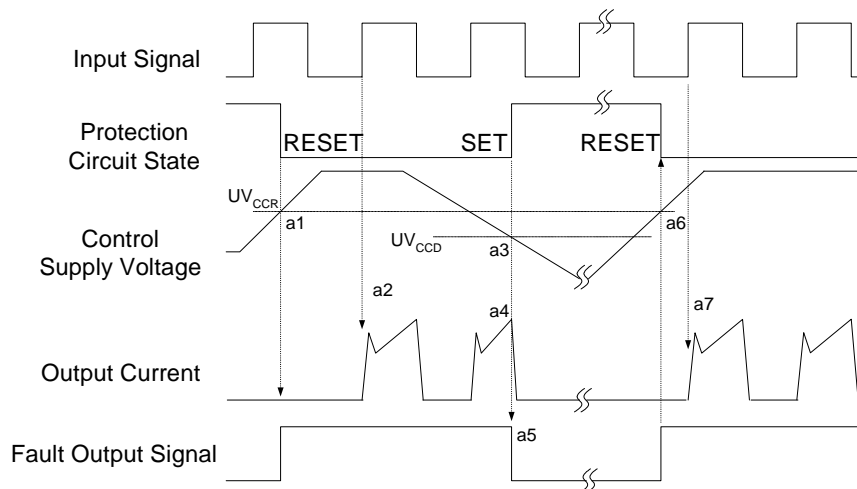


Figure 6. Flatness Measurement Position

Time Charts of Protective Function



- a1 : Control supply voltage rises: after the voltage rises UV_{CCR} , the circuits start to operate when the next input is applied.
- a2 : Normal operation: IGBT ON and carrying current.
- a3 : Under-voltage detection (UV_{CCD}).
- a4 : IGBT OFF in spite of control input condition.
- a5 : Fault output operation starts.
- a6 : Under-voltage reset (UV_{CCR}).
- a7 : Normal operation: IGBT ON and carrying current.

Figure 7. Under-Voltage Protection

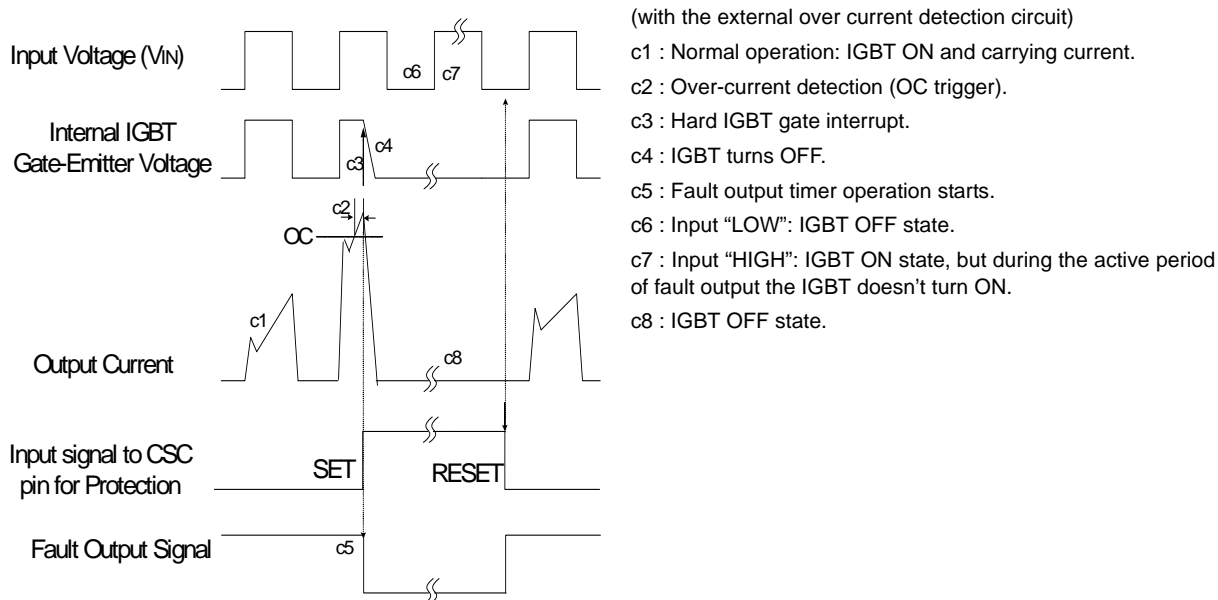


Figure 8. Over-Current Protection

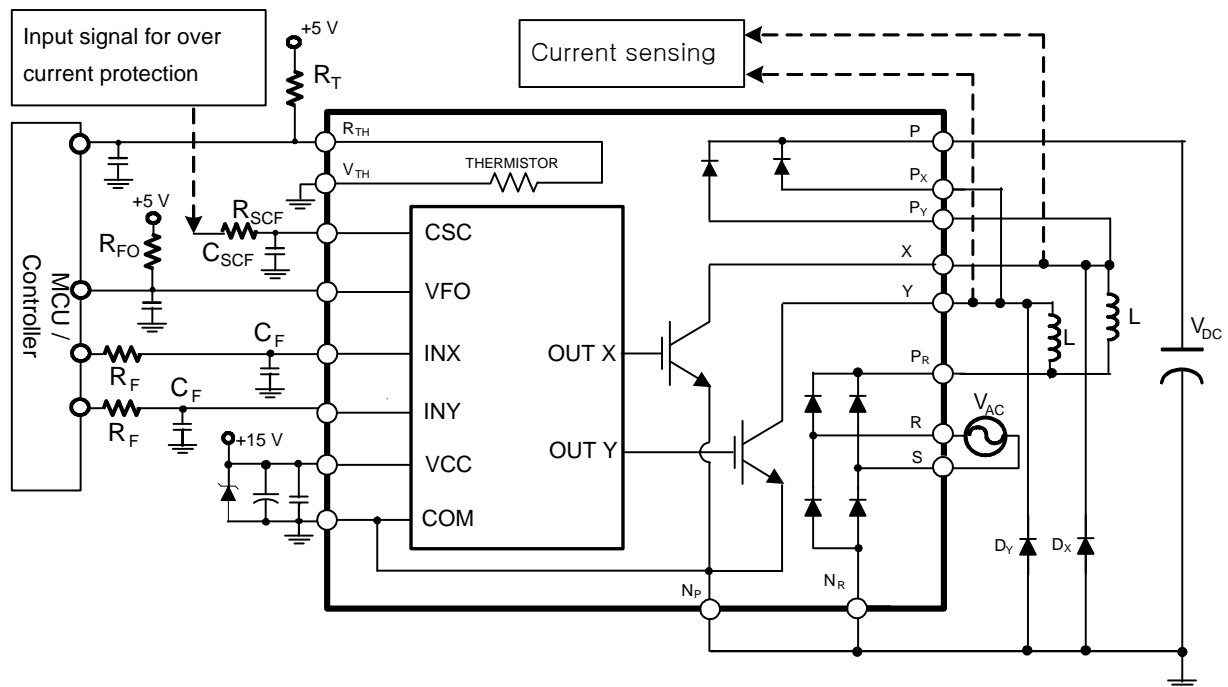
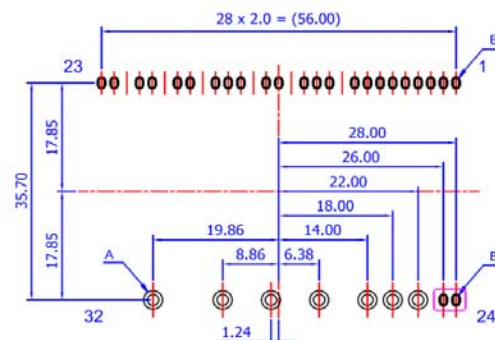
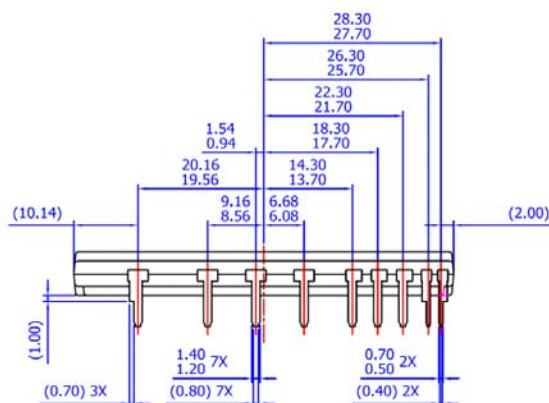
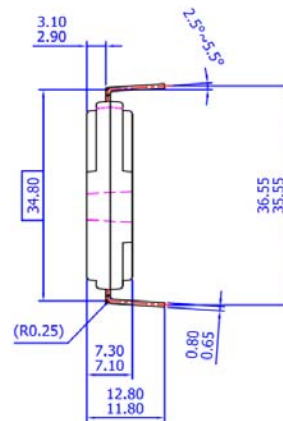
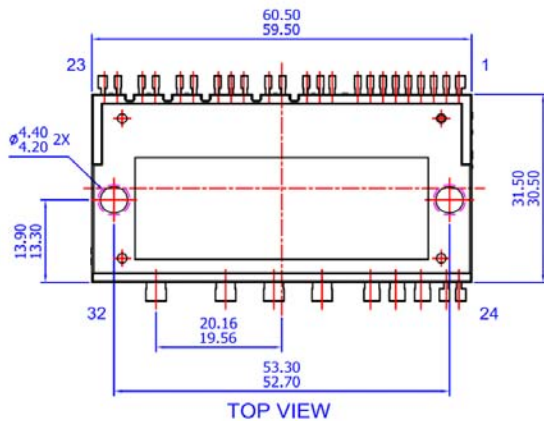
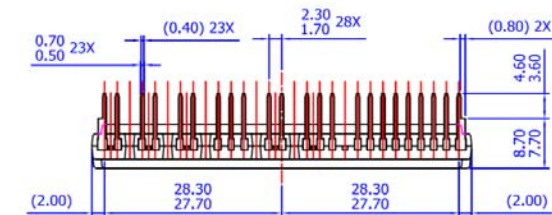


Figure 9. Typical Application Circuit

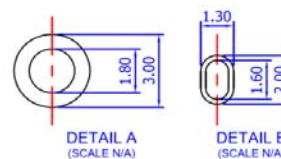
2nd Notes:

1. To avoid malfunction, the wiring of each input should be as short as possible (less than 2 ~ 3 cm).
2. V_{FO} output is open-drain type. This signal line should be pulled up to the positive-side of the MCU or control power supply with a resistor that makes I_{FO} up to 1 mA.
3. Input signal is active-HIGH type. There is a $5\text{ k}\Omega$ resistor inside the IC to pull-down each input signal line to GND. RC coupling circuits is recommended for the prevention of input signal oscillation. $R_F C_F$ constant should be selected in the range 50~150ns (recommended $R_F = 100\text{ }\Omega$, $C_F = 1\text{ nF}$).
4. To prevent error of the protection function, the wiring related with R_{SCF} and C_{SCF} should be as short as possible.
5. In the over current protection circuit, please select the R_{SCF} , C_{SCF} time constant in the range 1.5 ~ 2 μs .
6. Each capacitors should be mounted as close to the PFC SPM® product pins as possible.
7. Relays are used at almost every systems of electrical equipments of home appliances. In these cases, there should be sufficient distance between the MCU / controller and the relays.
8. Internal NTC thermistor can be used for monitoring of the case temperature and protecting the device from the overheating operation. Select an appropriate resistor R_T according to the application.
9. It is recommended that anti-parallel diode (D_X , D_Y) be connected with each IGBT.

Detailed Package Outline Drawings



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